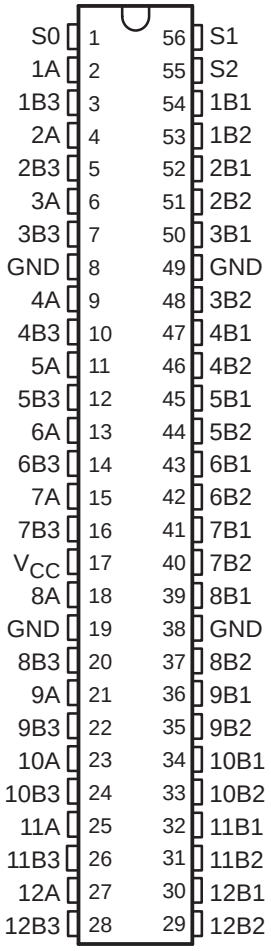
- **Member of the Texas Instruments Widebus™ Family**
- **Undershoot Protection for Off-Isolation on A and B Ports Up To −2 V**
- **Bidirectional Data Flow, With Near-Zero Propagation Delay**
- **Low ON-State Resistance (r_{on}) Characteristics (r_{on} = 3 Ω Typical)**
- **Low Input/Output Capacitance Minimizes Loading and Signal Distortion ($C_{io(OFF)}$ = 5.5 pF Typical)**
- **Data and Control Inputs Provide Undershoot Clamp Diodes**
- **Low Power Consumption (I_{CC} = 3 μA Max)**
- **V_{CC} Operating Range From 4 V to 5.5 V**
- **Data I/Os Support 0 to 5-V Signaling Levels (0.8-V, 1.2-V, 1.5-V, 1.8-V, 2.5-V, 3.3-V, 5-V)**
- **Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Performance Tested Per JESD 22**
  - **2000-V Human-Body Model (A114-B, Class II)**
  - **1000-V Charged-Device Model (C101)**
- **Supports Both Digital and Analog Applications: PCI Interface, Bus Isolation, Low-Distortion Signal Gating**

DGG OR DL PACKAGE
(TOP VIEW)



description/ordering information

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SSOP − DL	Tube	SN74CBT16214CDL	CBT16214C
		Tape and reel	SN74CBT16214CDLR	
	TSSOP − DGG	Tube	SN74CBT16214CDGG	CBT16214C
		Tape and reel	SN74CBT16214CDGGR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

description/ordering information (continued)

The SN74CBT16214C is a high-speed TTL-compatible FET multiplexer/demultiplexer with low ON-state resistance (r_{on}), allowing for minimal propagation delay. Active Undershoot-Protection Circuitry on the A and B ports of the SN74CBT16214C provides protection for undershoot up to −2 V by sensing an undershoot event and ensuring that the switch remains in the proper OFF state.

The SN74CBT16214C is a 12-bit 1-of-3 multiplexer/demultiplexer. The select (S0, S1, S2) inputs control the data path of each multiplexer/demultiplexer. When the multiplexer/demultiplexer is enabled, the A port is connected to the B port, allowing bidirectional data flow between ports. When the multiplexer/demultiplexer is disabled, a high-impedance state exists between the A and B ports.

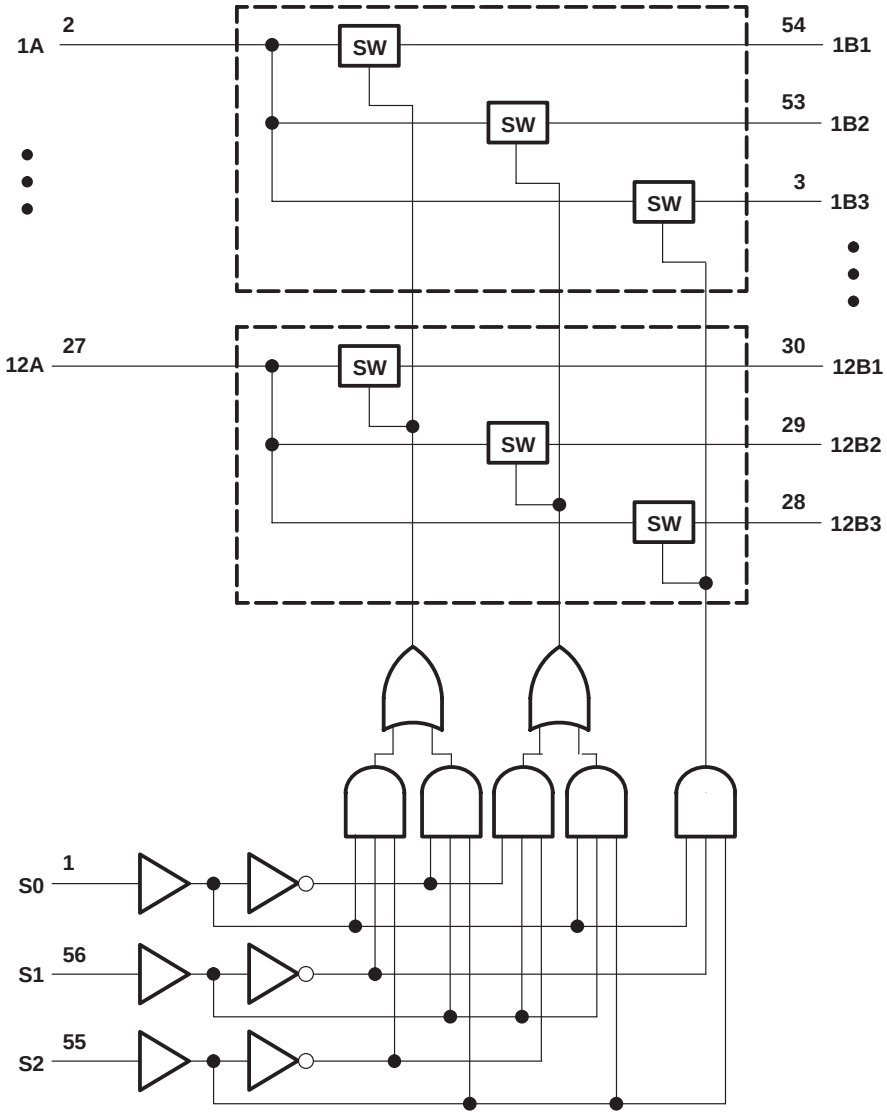
This device is fully specified for partial-power-down applications using I_{off}. The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down, each select input should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

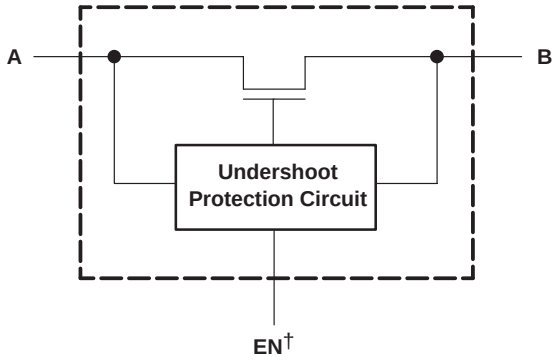
FUNCTION TABLE

INPUTS			INPUT/OUTPUT A	FUNCTION
S2	S1	S0		
L	L	L	Z	Disconnect
L	L	H	B1	A port = B1 port
L	H	L	B2	A port = B2 port
L	H	H	Z	Disconnect
H	L	L	Z	Disconnect
H	L	H	B3	A port = B3 port
H	H	L	B1	A port = B1 port
H	H	H	B2	A port = B2 port

logic diagram (positive logic)



simplified schematic, each FET switch (SW)



† EN is the internal enable signal applied to the switch.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Control input voltage range, V_{IN} (see Notes 1 and 2) . . . . . −0.5 V to 7 V
Switch I/O voltage range, $V_{I/O}$ (see Notes 1, 2, and 3) . . . . . −0.5 V to 7 V
Control input clamp current, I_{IK} (V_{IN} < 0) . . . . . −50 mA
I/O port clamp current, $I_{I/OK}$ ($V_{I/O}$ < 0) . . . . . −50 mA
ON-state switch current, $I_{I/O}$ (see Note 4) . . . . . ±128 mA
Continuous current through V_{CC} or GND terminals . . . . . ±100 mA
Package thermal impedance, θ_{JA} (see Note 5): DGG package . . . . . 64°C/W
DL package . . . . . 56°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to ground unless otherwise specified.
2. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
3. V_I and V_O are used to denote specific conditions for $V_{I/O}$.
4. I_I and I_O are used to denote specific conditions for $I_{I/O}$.
5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 6)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	4	5.5	V
V_{IH}	High-level control input voltage	2	5.5	V
V_{IL}	Low-level control input voltage	0	0.8	V
$V_{I/O}$	Data input/output voltage	0	5.5	V
T_A	Operating free-air temperature	−40	85	°C

NOTE 6: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IK}	Control inputs	V_{CC} = 4.5 V,	I_{IN} = −18 mA				−1.8	V
V_{IKU}	Data inputs	V_{CC} = 5 V,	0 mA > I_I ≥ −50 mA, V_{IN} = V_{CC} or GND,	Switch OFF			−2	V
I_{IN}	Control inputs	V_{CC} = 5.5 V,	V_{IN} = V_{CC} or GND				±1	μA
I_{OZ}‡		V_{CC} = 5.5 V,	V_O = 0 to 5.5 V, V_I = 0,	Switch OFF, V_{IN} = V_{CC} or GND			±10	μA
I_{off}		V_{CC} = 0,	V_O = 0 to 5.5 V,	V_I = 0			10	μA
I_{CC}		V_{CC} = 5.5 V,	$I_{I/O}$ = 0, V_{IN} = V_{CC} or GND,	Switch ON or OFF			3	μA
ΔI_{CC}§	Control inputs	V_{CC} = 5.5 V,	One input at 3.4 V,	Other inputs at V_{CC} or GND			2.5	mA
C_{in}	Control inputs	V_{IN} = 3 V or 0				3.5		pF
$C_{io(OFF)}$	A port	$V_{I/O}$ = 3 V or 0,	Switch OFF,	V_{IN} = V_{CC} or GND		10		pF
	B port					5.5		pF
$C_{io(ON)}$		$V_{I/O}$ = 3 V or 0,	Switch ON,	V_{IN} = V_{CC} or GND		18		pF
r_{on}¶		V_{CC} = 4 V, TYP at V_{CC} = 4 V	V_I = 2.4 V,	I_O = −15 mA		8	12	Ω
		V_{CC} = 4.5 V	V_I = 0	I_O = 64 mA		3	6	Ω
				I_O = 30 mA		3	6	Ω
			V_I = 2.4 V,	I_O = −15 mA		5	10	Ω

V_{IN} and I_{IN} refer to control inputs. V_I, V_O, I_I, and I_O refer to data pins.
† All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This is the increase in supply current for each input that is at the specified voltage level, rather than V_{CC} or GND.
¶ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4 V		V_{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t_{pd}#	A or B	B or A		0.24		0.15	ns
$t_{pd(s)}$	S	A		6.7	1.5	6.3	ns
t_{en}	S	B		7.2	1.5	6.6	ns
t_{dis}	S	B		7.5	1.5	7.3	ns

The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

undershoot characteristics (see Figures 1 and 2)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OUTU}	V_{CC} = 5.5 V, Switch OFF, V_{IN} = V_{CC} or GND	2	V_{OH}–0.3		V

† All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

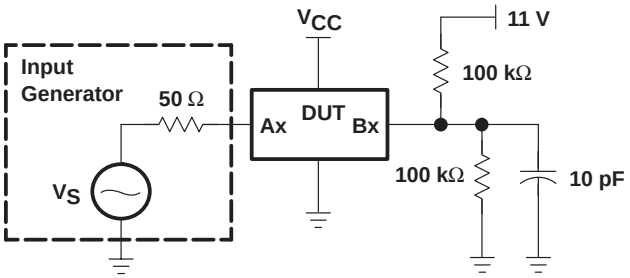


Figure 1. Device Test Setup

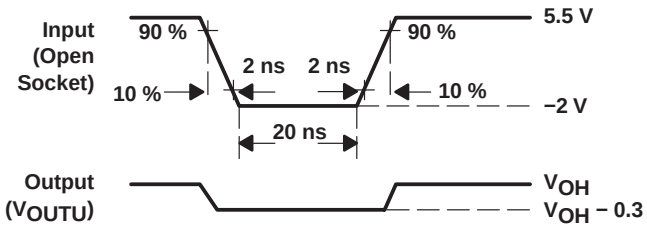
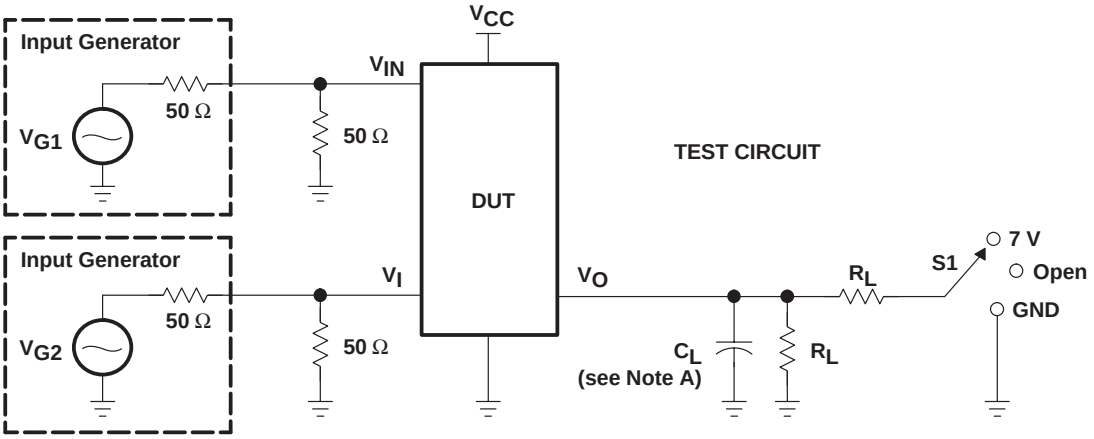
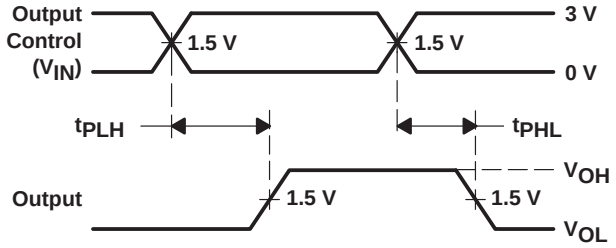


Figure 2. Transient Input Voltage (V_I) and Output Voltage (V_{OUTU}) Waveforms (Switch OFF)

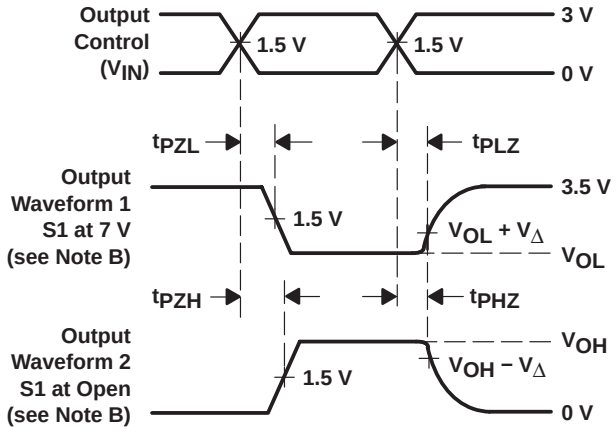
PARAMETER MEASUREMENT INFORMATION



TEST	V_{CC}	S1	R_L	V_I	C_L	V_Δ
$t_{pd(s)}$	5 V ± 0.5 V 4 V	Open Open	500 Ω 500 Ω	V_{CC} or GND V_{CC} or GND	50 pF 50 pF	
t_{PLZ}/t_{PZL}	5 V ± 0.5 V 4 V	7 V 7 V	500 Ω 500 Ω	GND GND	50 pF 50 pF	0.3 V 0.3 V
t_{PHZ}/t_{PZH}	5 V ± 0.5 V 4 V	Open Open	500 Ω 500 Ω	V_{CC} V_{CC}	50 pF 50 pF	0.3 V 0.3 V



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES ($t_{pd(s)}$)



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as $t_{pd(s)}$. The tpd propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
H. All parameters and waveforms are not applicable to all devices.

Figure 3. Test Circuit and Voltage Waveforms

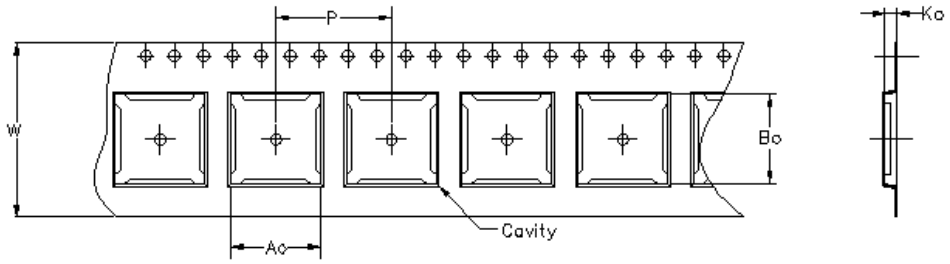
PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
74CBT16214CDGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214CDGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214CDL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214CDLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214CDLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214CDLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

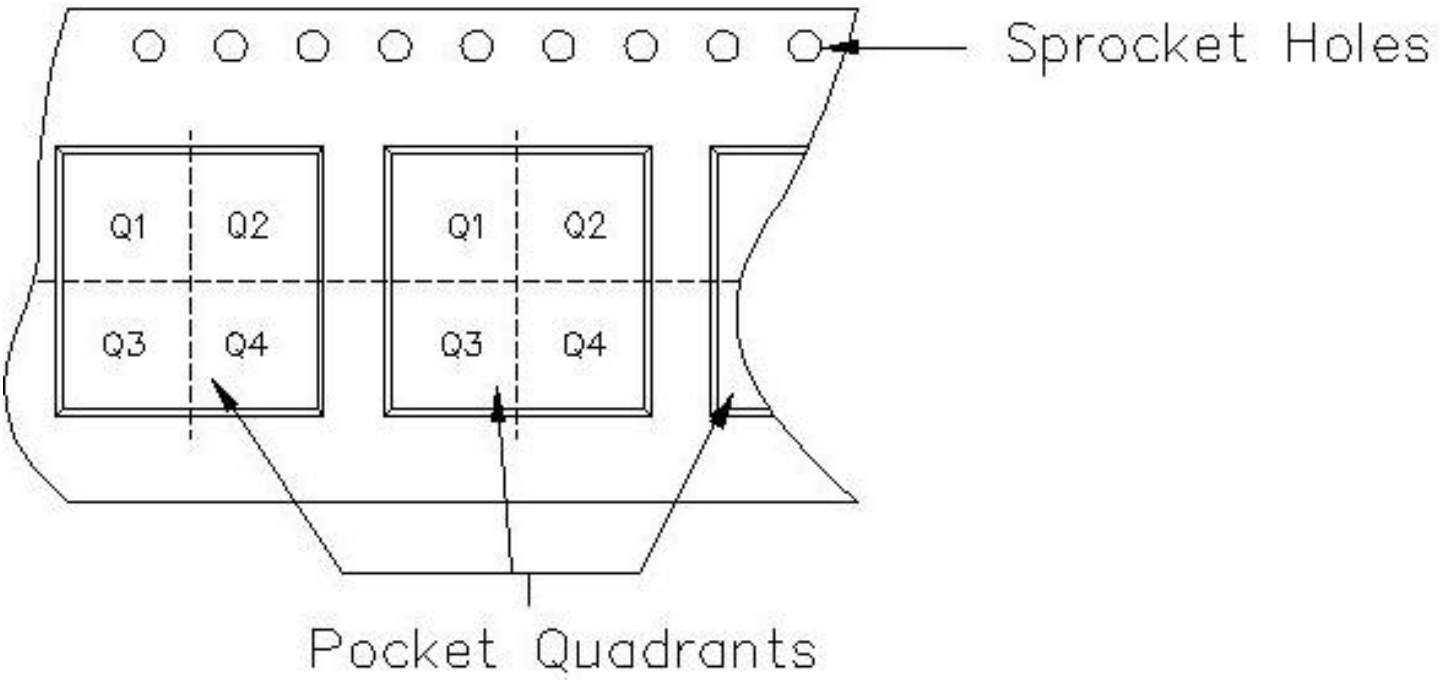
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



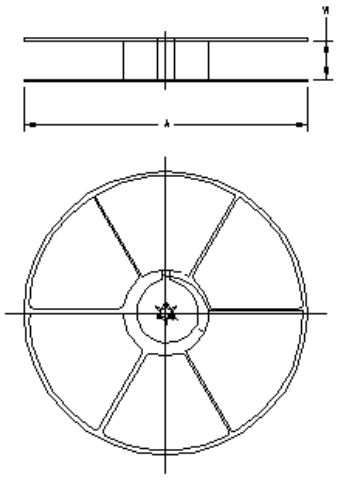
Carrier tape design is defined largely by the component lentgh, width, and thickness.

Ao = Dimension designed to accommodate the component width.
Bo = Dimension designed to accommodate the component length.
Ko = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



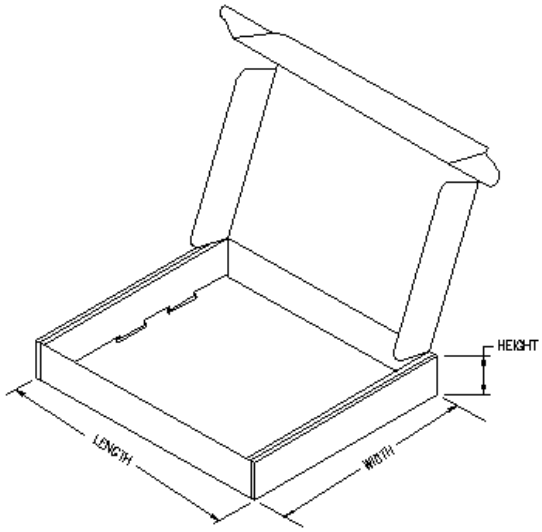
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16214CDGGR	DGG	56	MLA	330	24	8.6	15.8	1.8	12	24	Q1
SN74CBT16214CDLR	DL	56	MLA	330	32	11.35	18.67	3.1	16	32	Q1



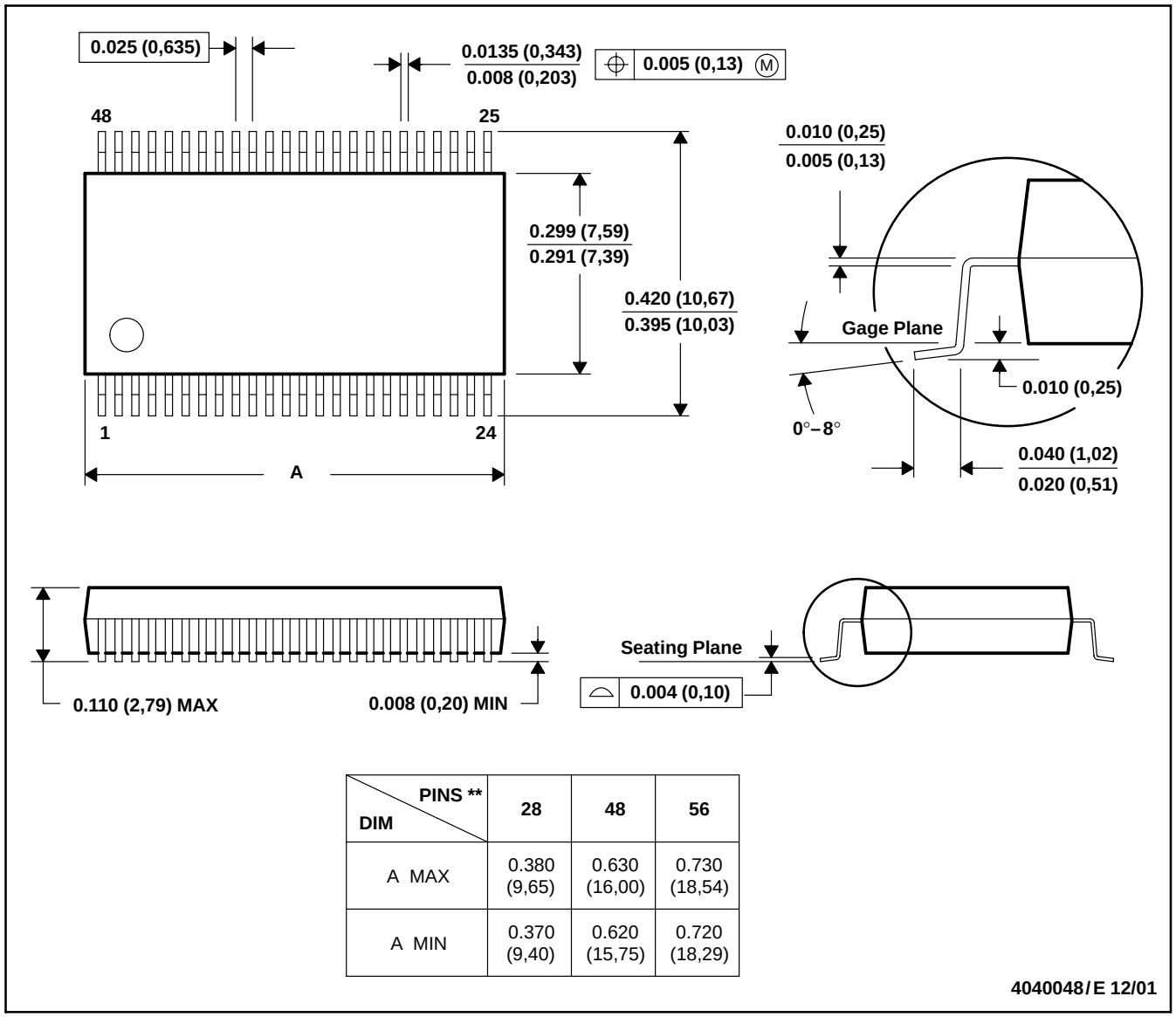
TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74CBT16214CDGGR	DGG	56	MLA	333.2	333.2	31.75
SN74CBT16214CDLR	DL	56	MLA	336.6	342.9	41.3



DL (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN



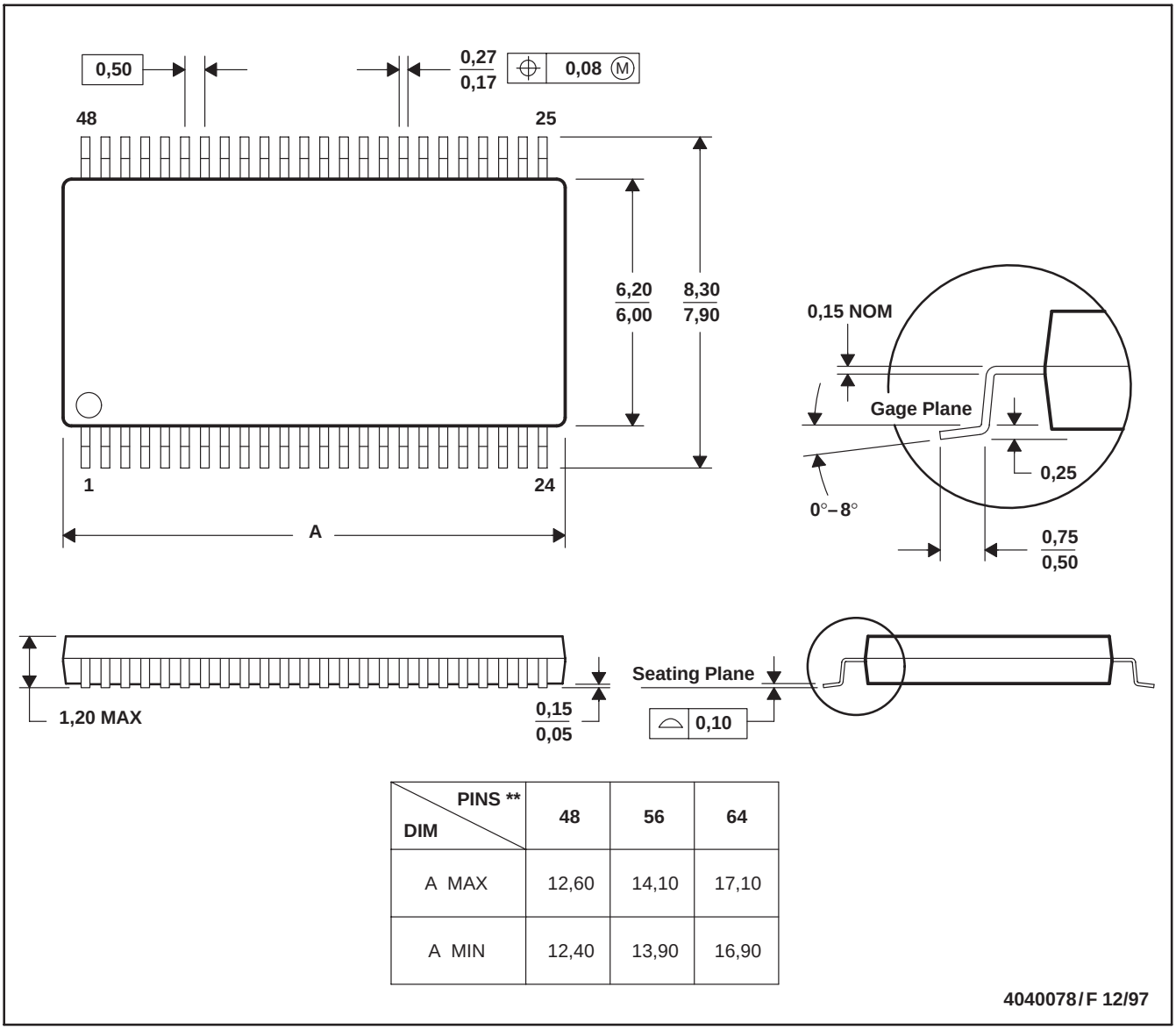
DIM \ PINS **	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

4040048/E 12/01

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MO-118

DGG (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN



DIM \ PINS **	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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